

CLAIMS

1. A film carrier tape for mounting electronic components, which tape comprises an insulating film and, on the surface thereof, an inner connection terminal, an outer connection
5 terminal and a wiring for connecting these terminals and further comprises a solder resist layer covered in such a way that the connection terminals are exposed, and which tape secures electric connection of a connection terminal of an electronic component and the inner connection terminal by applying an
10 ultrasonic wave on the inner connection terminal in mounting the electronic component,

wherein wiring positioned from a part where the inner connection terminal is electrically connected with the connection terminal of the electronic component to the edge of
15 the solder resist layer and wiring in a 1000 μm length from the edge of the solder resist, which wiring is protected by the solder resist layer, are formed in an almost straight shape.

2. The film carrier tape for mounting electronic
20 components according to claim 1 wherein the inner connection terminal is a bonding pad, and the connection terminal of the electronic component and the bonding pad are electrically connected by wire bonding using a conductive metal thin wire.

3. The film carrier tape for mounting electronic components according to claim 1 or 2 wherein wiring positioned from the part where the inner connection terminal is electrically connected with the connection terminal of the electronic component to the edge of the solder resist layer and wiring in a 1000 μm length from the edge of the solder resist, which wiring is protected by the solder resist layer, are formed as to not have an inflection part at which wiring is sharply bended or curved.

4. The film carrier tape for mounting electronic components according to claim 1 or 2 wherein a wiring pattern comprising the inner connection terminal, the outer connection terminal and the wiring for connecting those connection terminals is formed by selectively etching an electrodeposited copper foil and at least the crystal structure of the inner connection terminal and the crystal structure of the electrodeposited copper foil for forming the wiring have identity before and after the wire bonding.

5. The film carrier tape for mounting electronic components according to claim 4 wherein the wiring pattern is

formed by selectively etching the electrodeposited copper foil having an average thickness of from 5 to 35 μm .